Product End-of-Life Disassembly Instructions

**Product Category:** Notebooks and Tablet PCs

**Marketing Name / Model**  
[List multiple models if applicable.]

HP ProBook 11 Education Edition G2

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

### 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm Mother Board</td>
<td>1</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries Battery pack;RTC</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries N/A</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps Panel</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations. N/A</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td>N/A</td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td>N/A</td>
<td>0</td>
</tr>
</tbody>
</table>
Components, parts and materials containing radioactive substances | N/A | 0

### 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Screwdriver #1 T8 Trox screwdriver</td>
<td>T8</td>
</tr>
<tr>
<td>Description #2 Cross screwdriver</td>
<td>Cross</td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

### 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Release Battery and Access Door
2. Disassemble Hinge Up
3. Release HDD or SSD Module
4. Disassemble U-case Ass’y from L case Ass’y (MB)
5. Disassemble MB from L-case Ass’y
6. Disassembly Bezel
7. Disassembly LCD/ Hinge Module
8. 

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Dunes 拆机步骤
1.1 Release Battery and Access Door

1. 拆卸Low case door screw rubber
2. 取battery, 螺丝为自带螺丝
2. 使用六角螺丝起子取出8颗六角螺丝（螺丝为同一料号）
4. 取下low door
1.2 Disassemble Hinge Up

1. 取下hinge screw
2. 取下LVDS Cable& antenna
3. 取下Hinge Up
拆機步驟

1.3 Release HDD or SSD Module
1.4、拆卸U-case module。

1. 取下下圖中所標識的螺絲。

2. 从Low case面取出KB Cable，然后Low case边缘为软胶，可以倾斜向下用力拆卸U-case，分离U-case时取出power/b ffc
1.5 Disassemble MB from L-case Ass’y

1. 取下兩顆M2 X L3的螺絲，取下MB
2. 取下MB上Thermal
1.6 Disassembly Bezel

1. 拆下 LCD Bezel, 注意地侧两个 hinge cap 处存在卡勾

TOUCH

NON TOUCH
1.7 Disassembly LCD/ Hinge Module

1. For NON TOUCH—取下4顆螺絲及LVDS CABLE, 取下LCD.
2. 取下6颗M2.5, L2的螺絲及4颗M2, L2的螺絲，取下Hinge

NON TOUCH                              TOUCH&NON TOUCH
2.1 裝機步驟：

按裝機步驟裝好後開機確認

- CCD
- Hinge
- LCD
- LCD Pazel
- LCD Module
- MB
- Speaker
- Battery
- Wireless lan
- HDD
- USB Board
- Touch Pad
- U-case
- Base unit
- NB
Thank You!